

ALN THERMAL JUMPERS

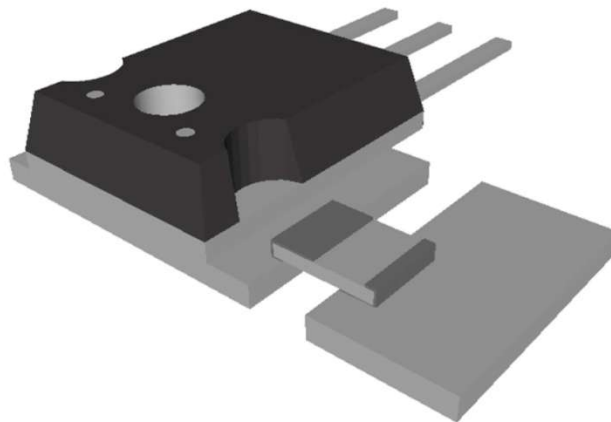
These ceramic chips are designed to help in thermal management by transferring the heat from components to an area on the PCB where it can be safely dissipated.

The thermal jumpers are electrically isolated and can be used in both, RF and DC applications.

These thermal jumpers are RoHS compliant and are ALN with different sizes and thickness. See other Data Sheets for BeO and CVD.



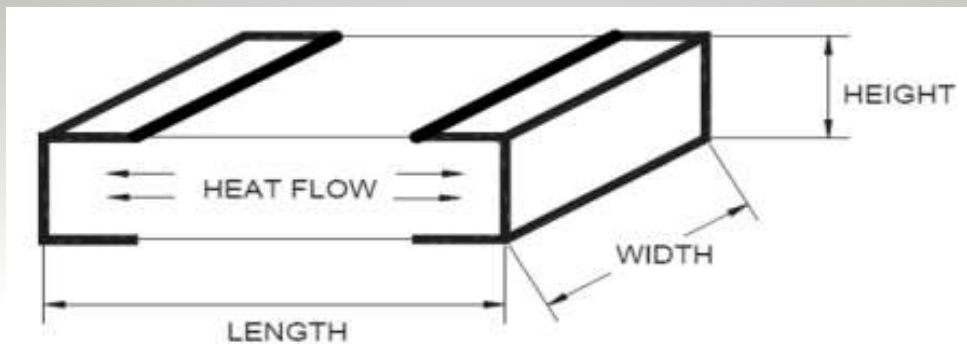
The Thermal Jumpers can be mounted between the chassis (or flange) of the heat source and an external heat sink providing a conduction path for the heat transfer creating a design alternative for systems where temperature cannot be controlled by forcing mechanisms like fans or water cooling systems.



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Metallization options: The thermal jumpers are offered with standard or extended metallization.

Standard Metallization:

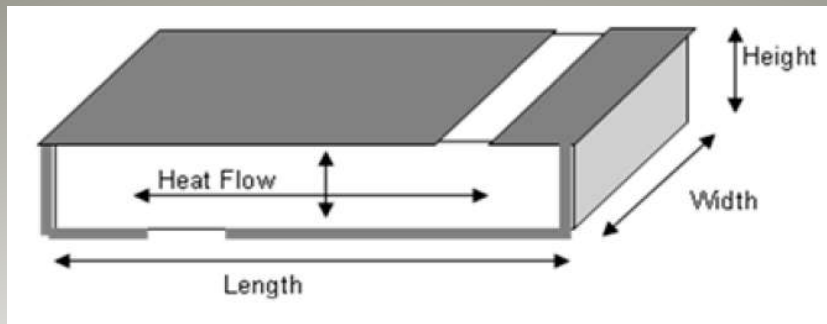


Aluminum Nitride

P/N	Length (in)	Width (in)	Thickness (in)	Thermal Resistance (°C/W)	Capacitance (pF)
RTC0505-25NW	0.050	0.050	0.025	9.2	0.150
RTC0603-25NW	0.060	0.030	0.025	18	0.075
RTC0805-25NW	0.080	0.050	0.025	15	0.070
RTC1005-25NW	0.100	0.050	0.025	18	0.042
RTC1206-25NW	0.120	0.060	0.025	18	0.038
RTC1020-25NW	0.100	0.200	0.025	4.63	0.170

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Extended Metallization: The extended metallization provides added heat transfer by increasing the effective area in the thermal path. This increased metallization will also increase the capacitance. This type of metallization is recommended for DC applications.



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P/N	Length (in)	Width (in)	Thickness (in)	Thermal Resistance (°C/W)	Capacitance (pF)
RTC0603-25NZ	0.060	0.030	0.025	4.3	0.200
RTC0805-25NZ	0.080	0.050	0.025	1.9	0.300
RTC1206-25NZ	0.120	0.060	0.025	0.9	0.600
RTC1020-40NZ	0.100	0.200	0.04	0.7	1.100

Ordering Information:

RTC 0505 - 25 N W

Series Number Size Thickness Substrate: Metallization:

N: Aluminum Nitride W: Standard Z: Extended